

ABSTRACT OF DISCLOSURE

An ESC (Electrostatic Chuck) to chuck an object by electrostatic force, having an ESC main body supporting the object; a guide ring supported by the ESC main body and encircling the object; a dielectric material layer interposed between the guide ring and the ESC main body; a media gas supplier to supply a media gas to the guide ring; and a power supplier to supply power to the ESC main body. With this configuration, the ESC provides an apparatus to chuck a guide ring to an ESC main body, while maintaining the guide ring and an object, such as a wafer, at the same or similar temperature, thereby enhancing uniformity of the object during a semiconductor manufacturing process such as etching, deposition, or the like.